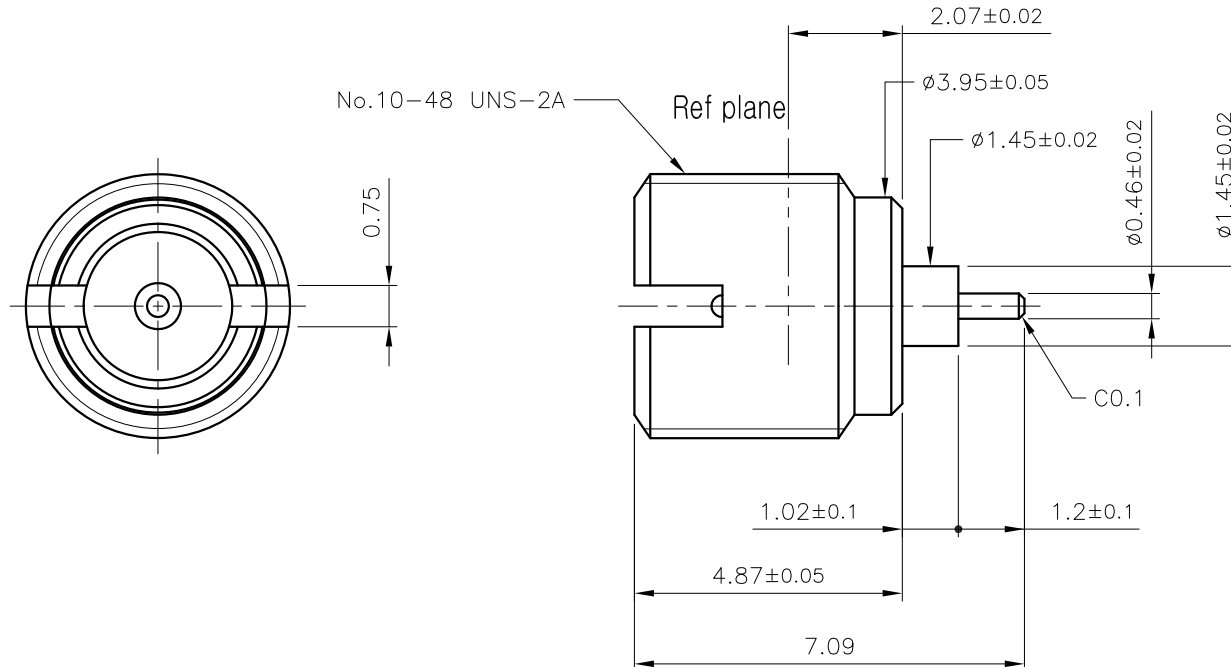


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1R	Initial Registration	S.H.KIM		2024.09.24.



3	INSULATOR	1	TEFLON		DIN03409-N/1
2	CONTACT	1	BeCu C17300	Gold Plate (1.27μm)	DCT04447-5/1
1	BODY	1	SUS303	Passivate	DBD04958-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2024. 09. 24.		 KJ COMTECH CO.,LTD.	RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY				
MATERIAL —		CHECKED BY		TITLE SMP50 SOLDER END PB (F/F) FULL DETENT		
		DRAWN BY	S.H.KIM			
FINISH —	SCALE 7/1	UNIT mm		A4	DWG NO. CN04149-7/1	
					REVISION	I R